ROC286CC

1U fanless 19” ,AC-DC Redundant Server

with Intel®

MIL-STD 810H

Power Automation Computer

- Intel® Coffee Lake-Refresh 8th/9th Processor(Up to 65W)
- 2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
- 1 x PCIex16 Slot
- 1 x M.2 (Key M, PCIex4 and SATA3) Expansion Slot
- 6 x USB, 3xDisplayPort, 2xLAN, 1xLine-out/Mic
- 2 x 2.5” SATA HDD/ SSD Easy Swap Tray

Specifications

System	
High Performance Processor	Socket LGA 1151 for Intel® Core i7/i5/i3/Celeron® (Supports up to 65W) Intel® 8th/9th Processor
Chipset	Intel® Q370 Chipset
Memory type	2 x DDR4 SO DIMM up to 64 GB
Expansion Slot	2 x SATAIII, 2.5" SSD
Display	
Display Port	Resolution up to 4096 x 2304 60@Hz
Storage	
HDD/SDD	2 x 2.5" SATA HDD/SSD easy swap tray
Ethernet	
Ethernet	Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps for x2 RJ45 ports)
Rear I/O	
Display Port	3x DP
Ethernet	2 x RJ45
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
COM	2 x RS232/422/485
USB Port	4 x USB 3.1(10Gb/s)
DC-IN	1 X 4P Terminal Block
Front I/O	
Button	1 x Power Button w/Indicator LED
Indicator LED	HDD
USB Port	2 x USB 2.0
Easy Swap SSD Tray	2
Power Requirement	
Power Input	9~36V DC IN
Applications, Operating System	
Applications	Commercial and Industrial Platforms, Embedded Computing, Process

	Control Intelligent Automation and manufacturing applications
Operating System	Windows 10 64Bit Ubuntu13.04, Ubuntu13.10, Ubuntu14.04, Fedora 20
Physical	
Dimension (W x D x H)	440x430 x 44 mm
Weight	8.92Kg
Chassis	SECC
Heatsink	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide
Environmental	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
Green Product	RoHS compliance
Operating Temperature	w/o Graphic Card (ET: -20 to 60°C; UT: -30 to 70°C) ; w/Graphic Card (0 to 50°C)
Storage Temperature	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing
EMC	CE and FCC compliance

Dimension